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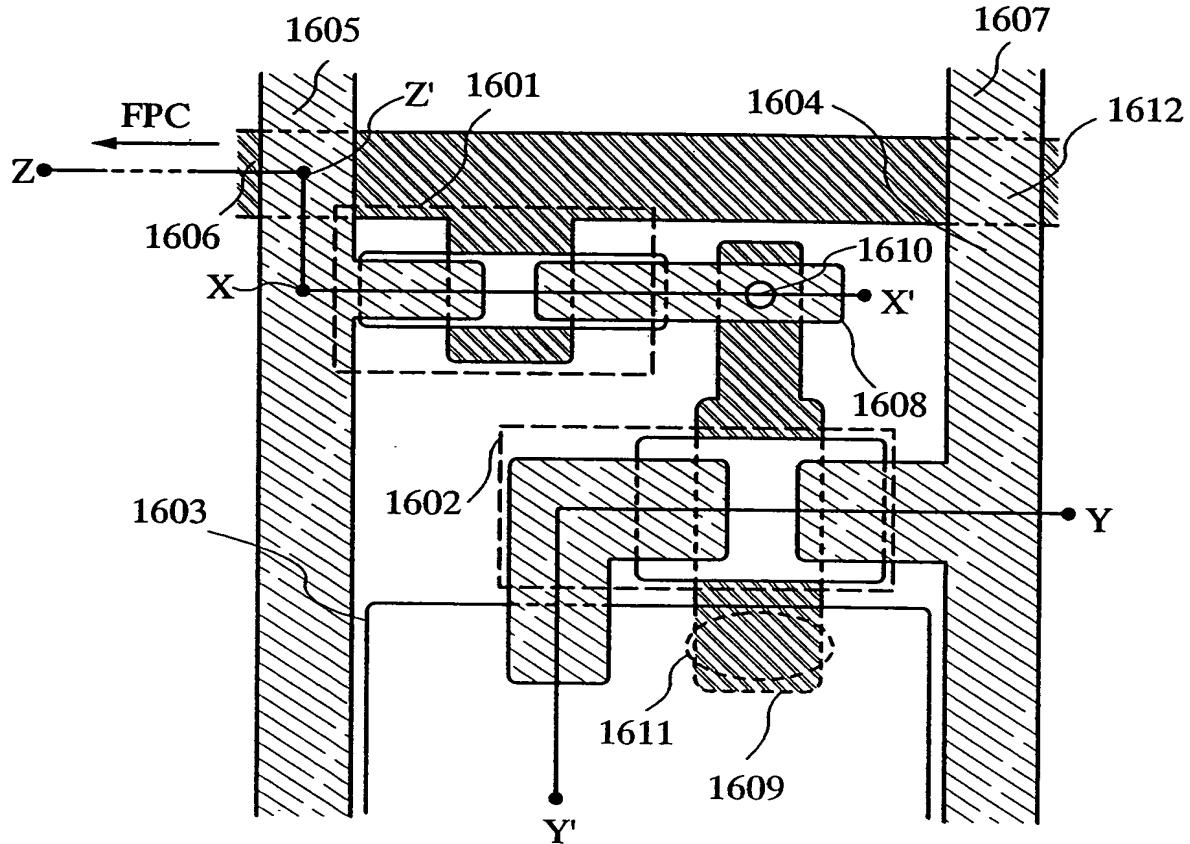


FIG.1A

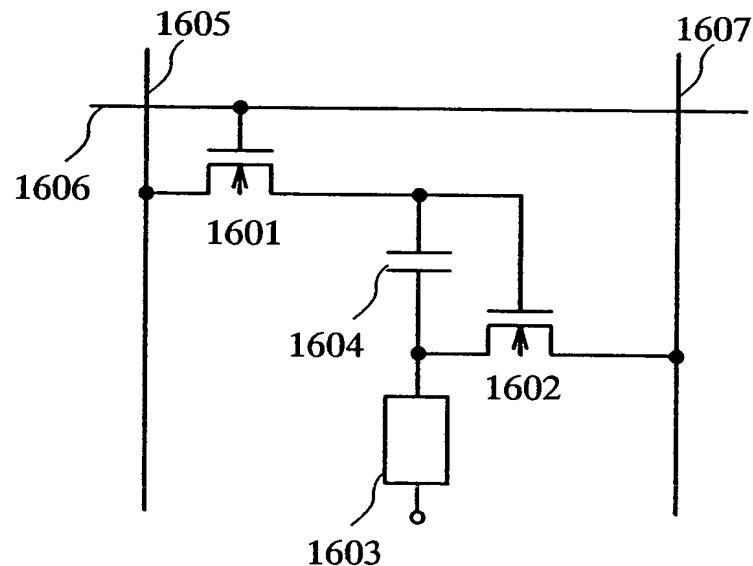


FIG.1B

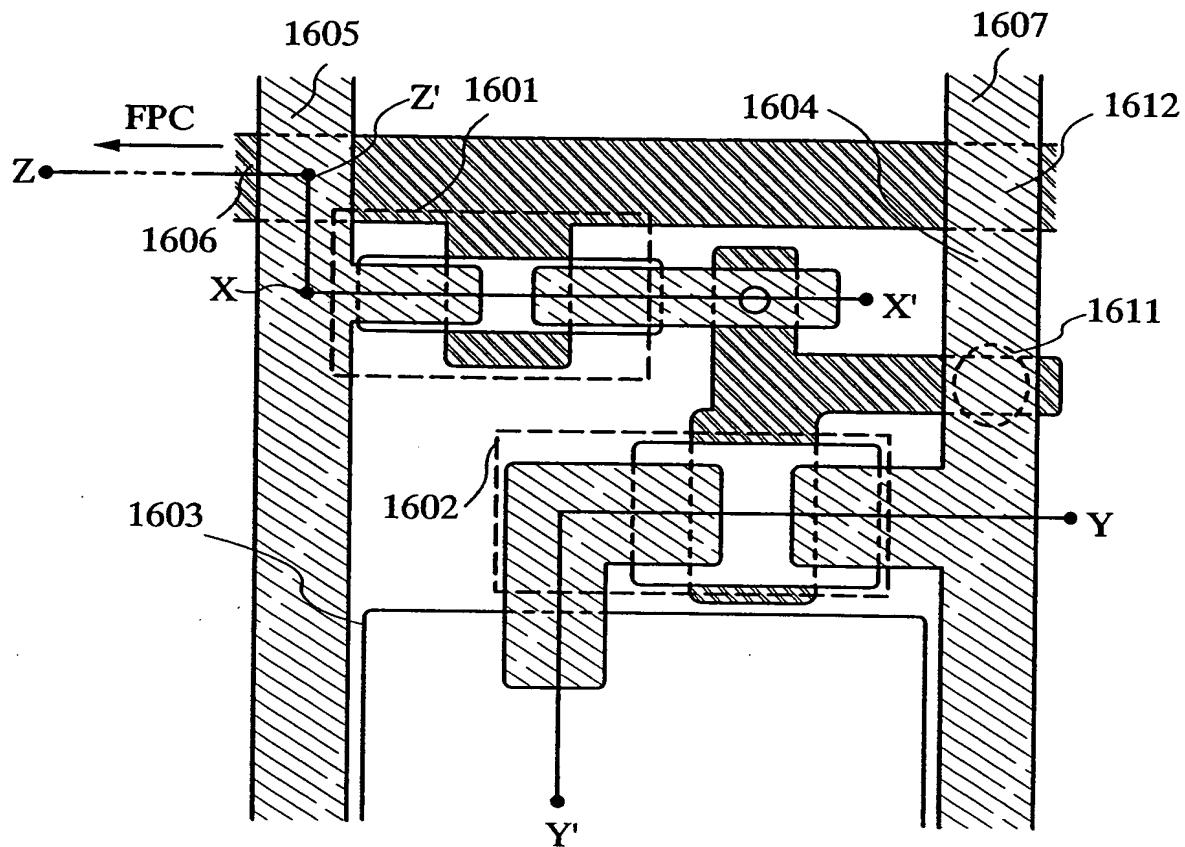


Fig.2A

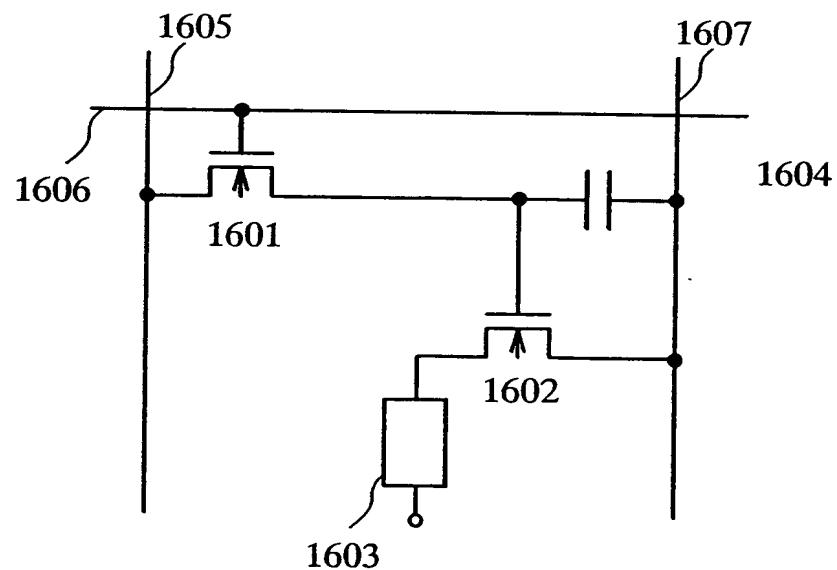


Fig.2B

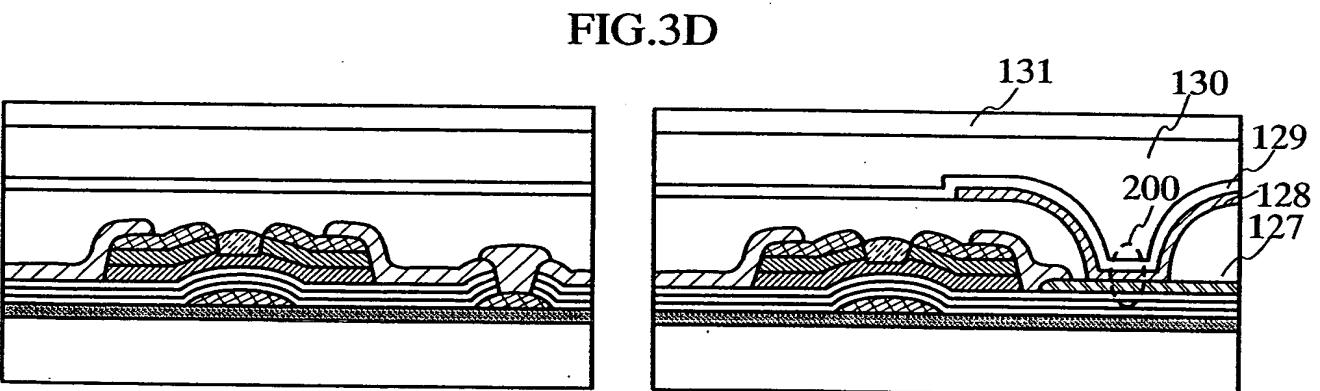
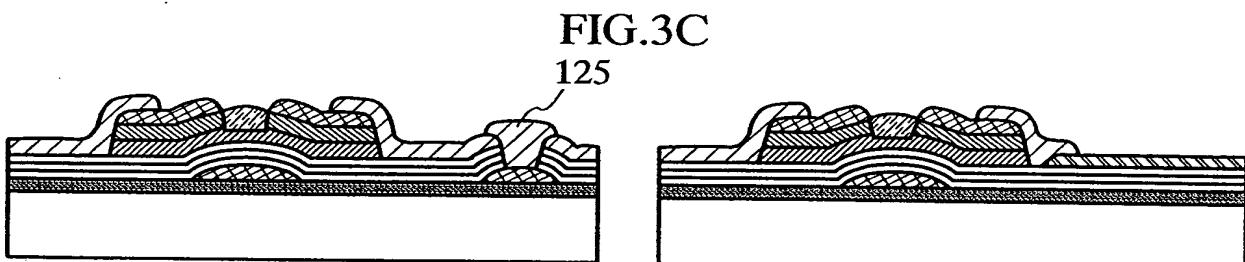
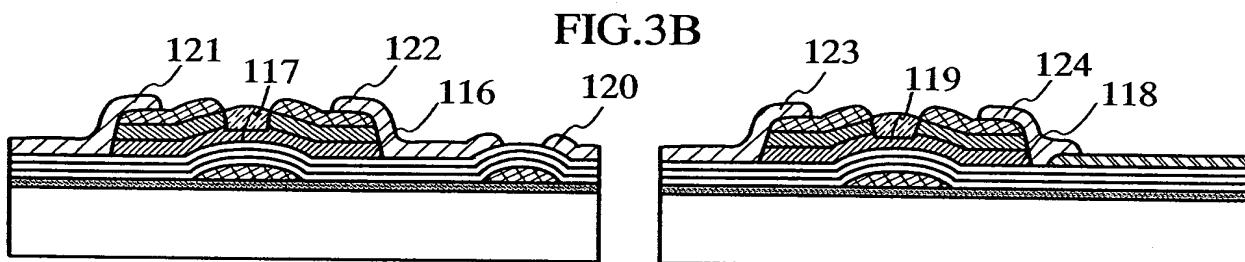
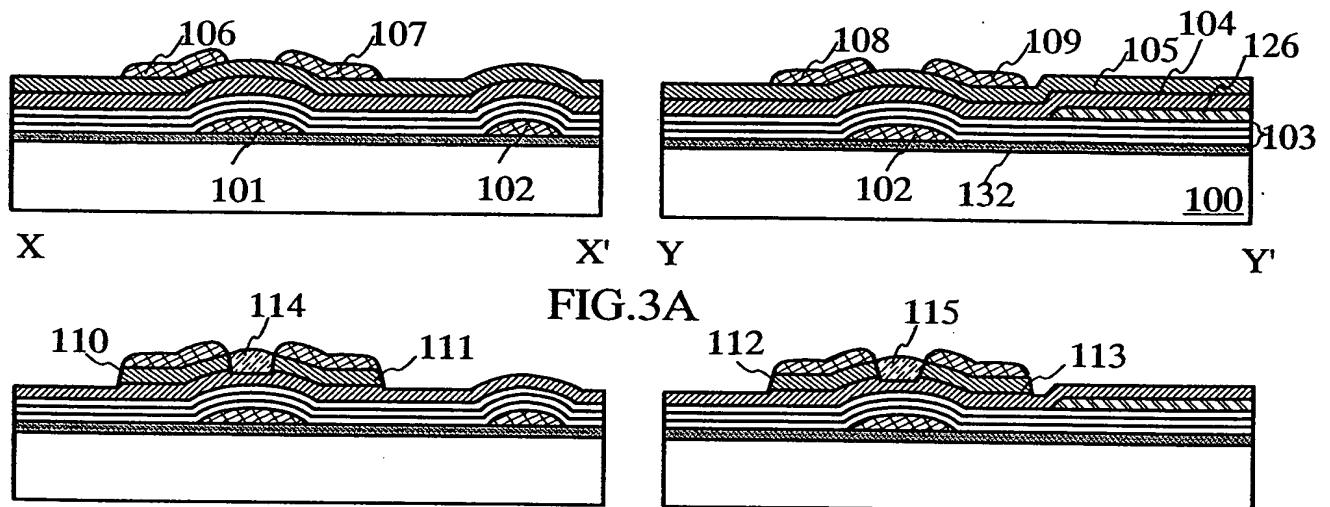
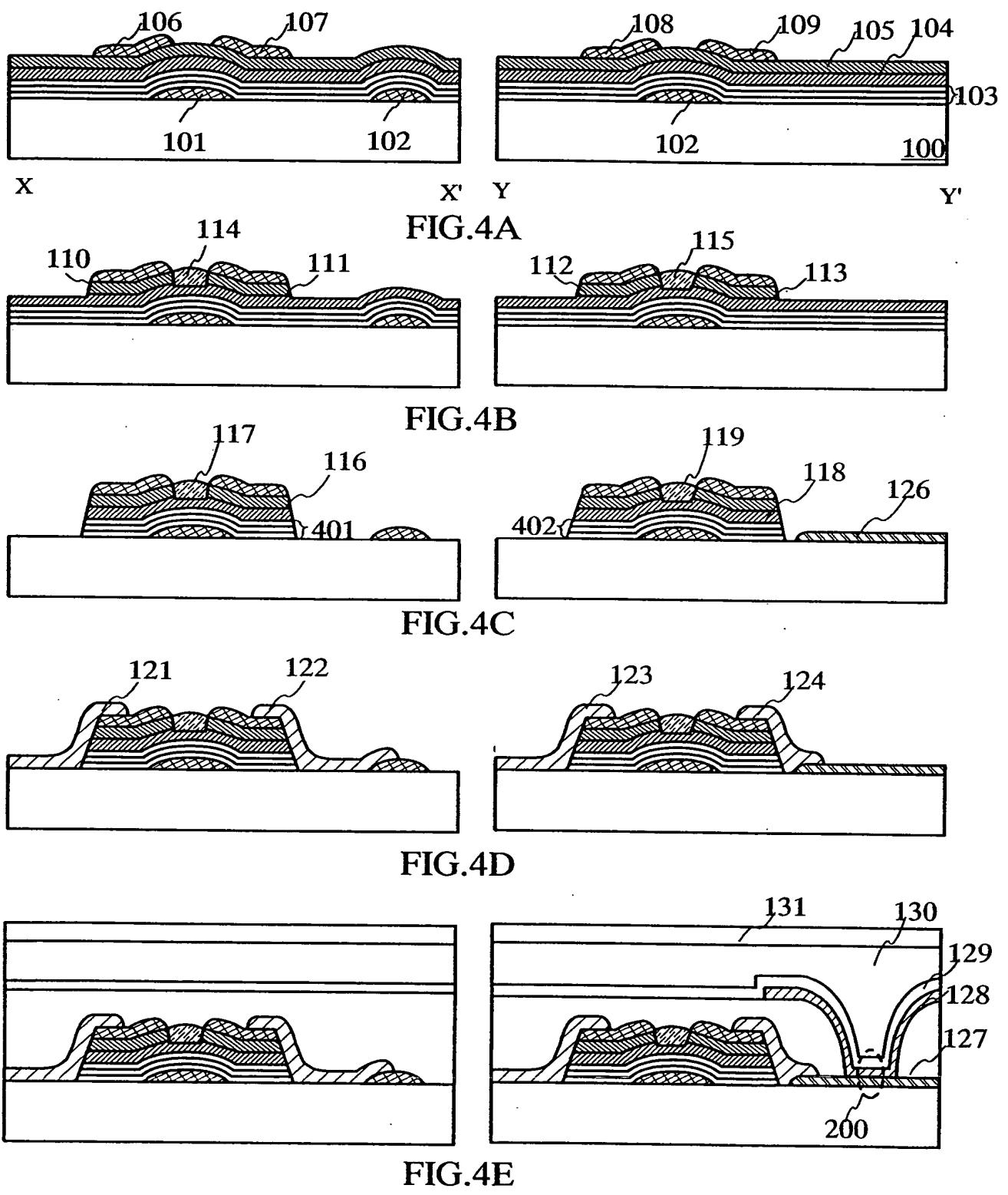


FIG.3E



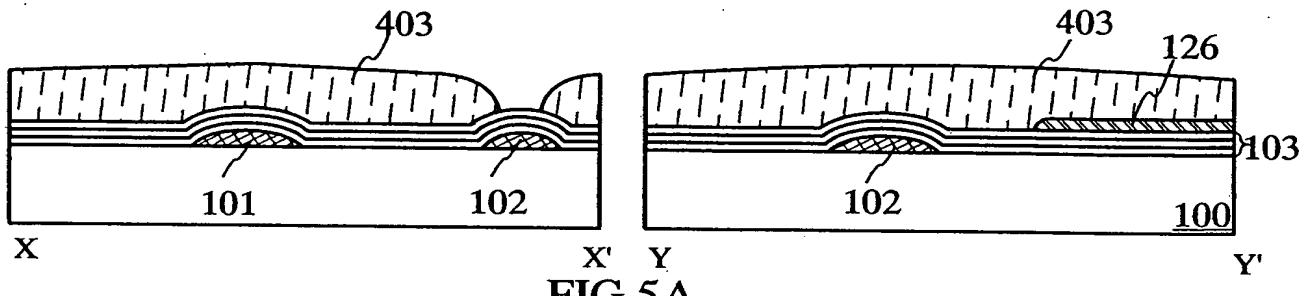


FIG. 5A

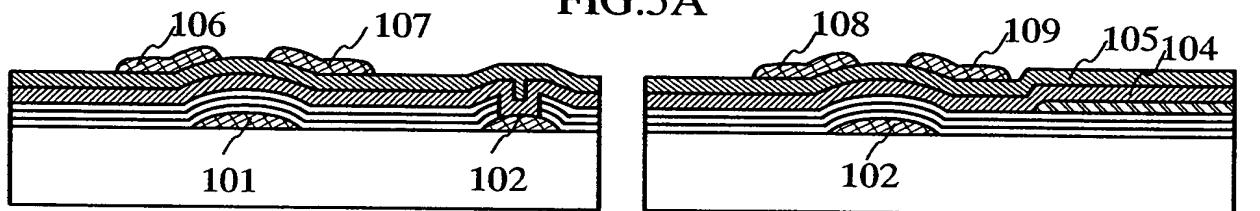


FIG. 5B

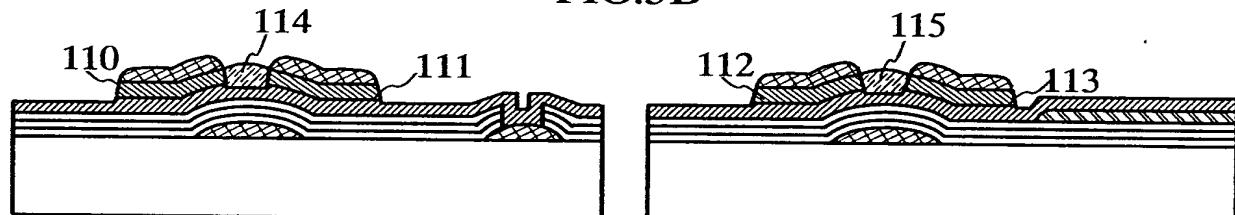


FIG. 5C

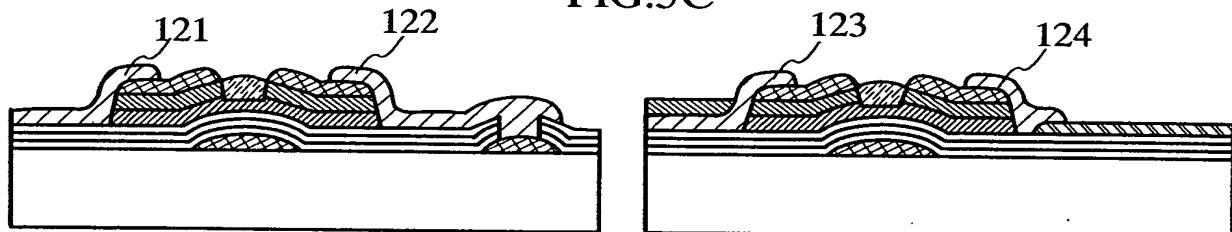


FIG. 5D

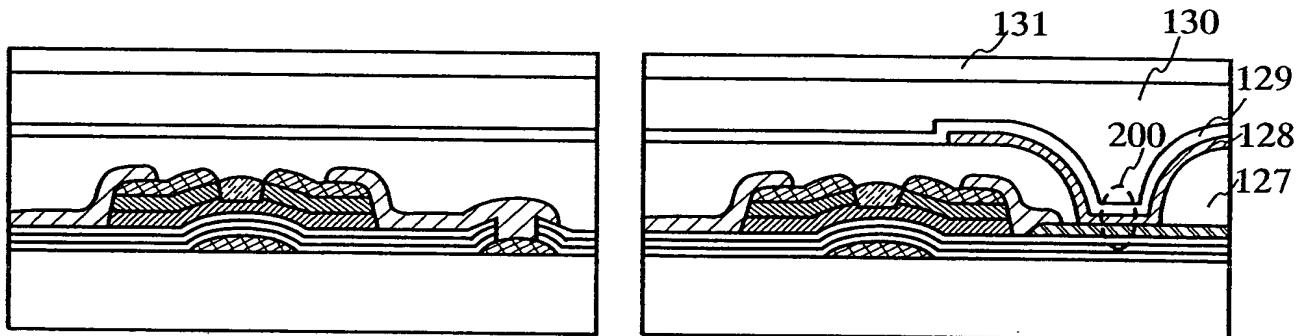


FIG. 5E

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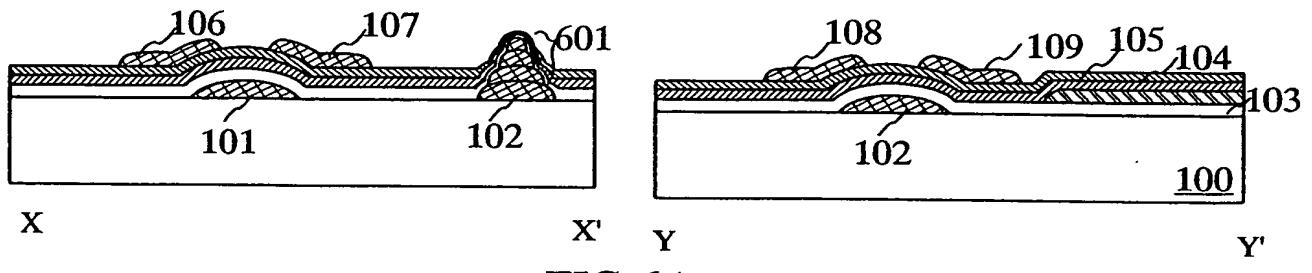


FIG. 6A

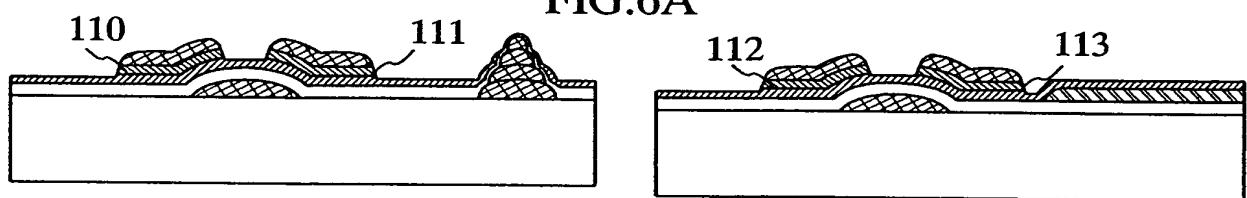


FIG. 6B

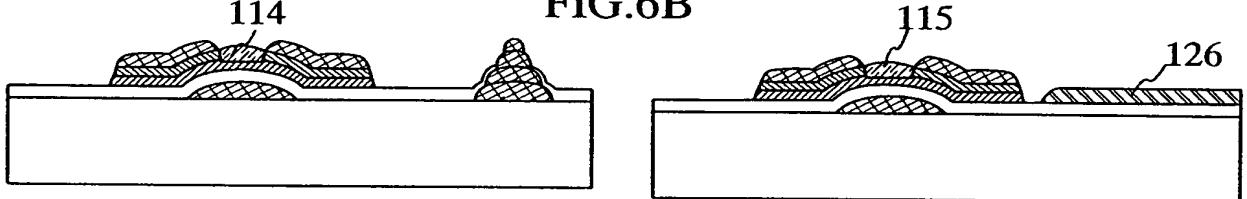


FIG. 6C

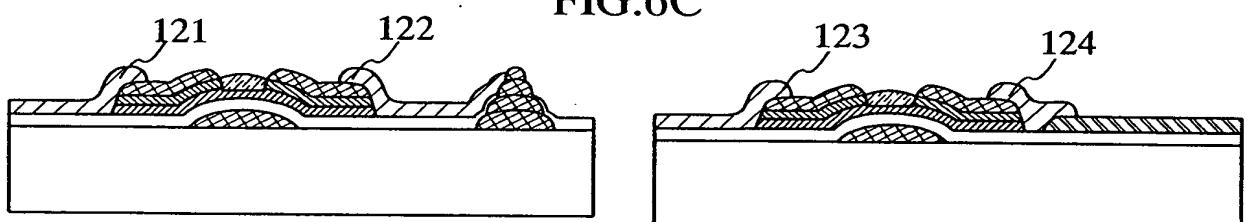


FIG. 6D

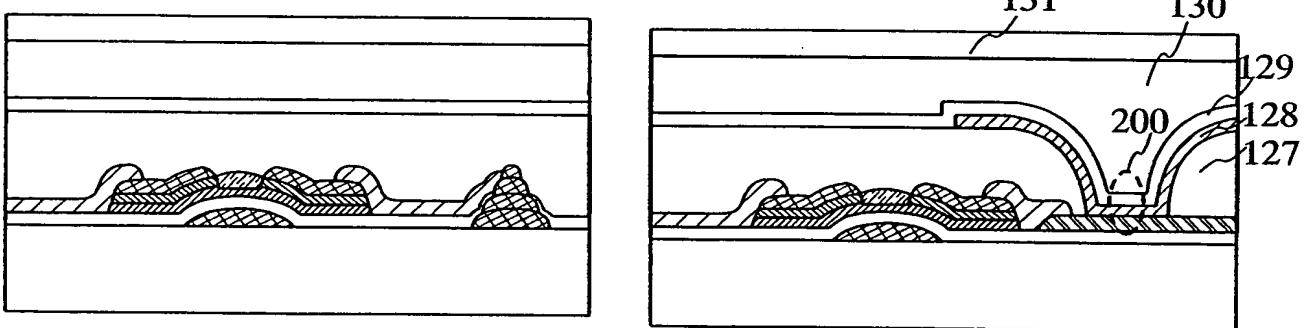


FIG. 6E

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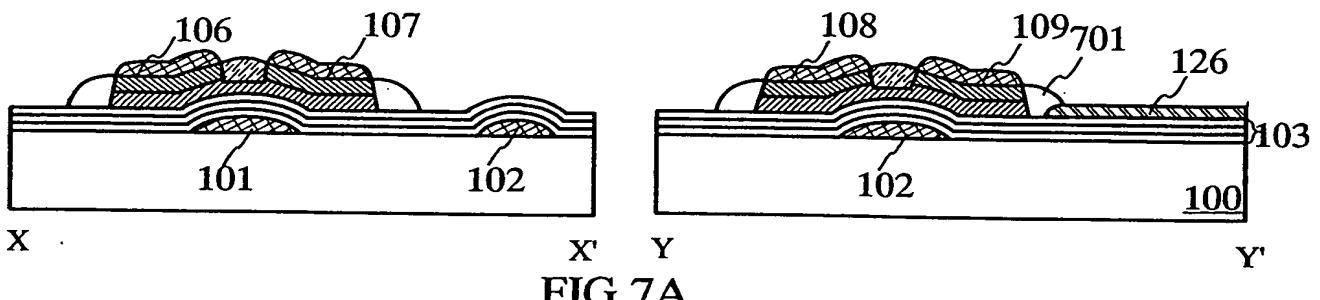


FIG. 7A

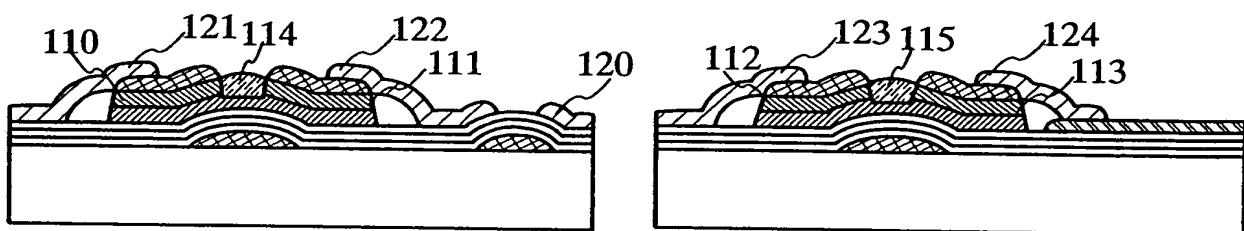


FIG. 7B

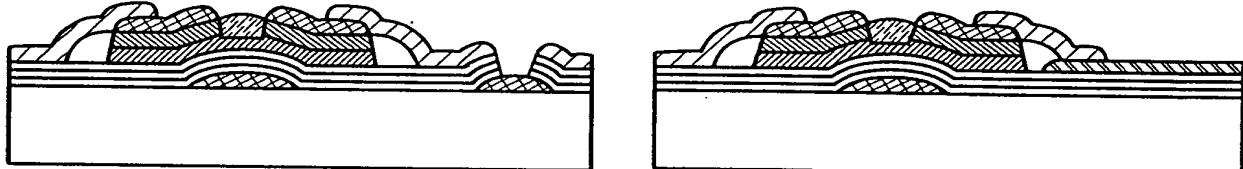


FIG. 7C

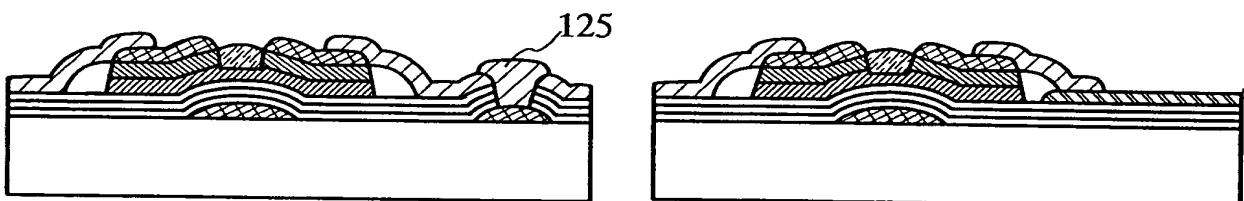


FIG. 7D

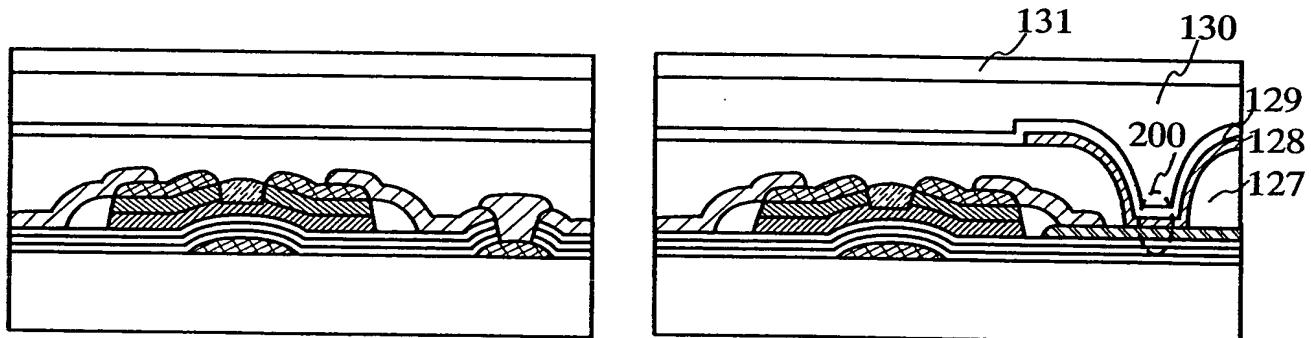


FIG. 7E

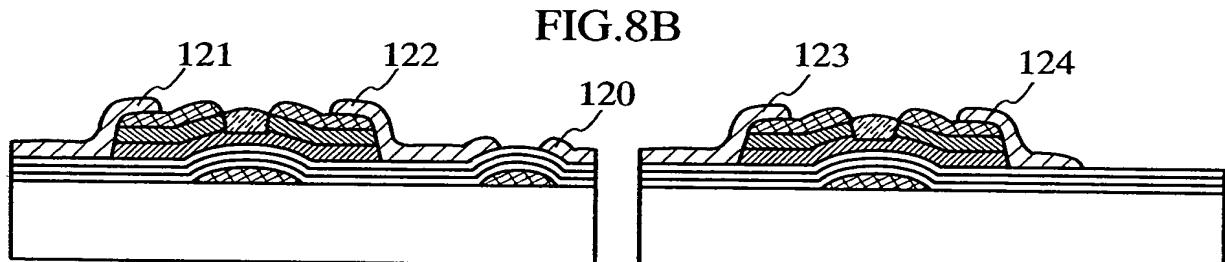
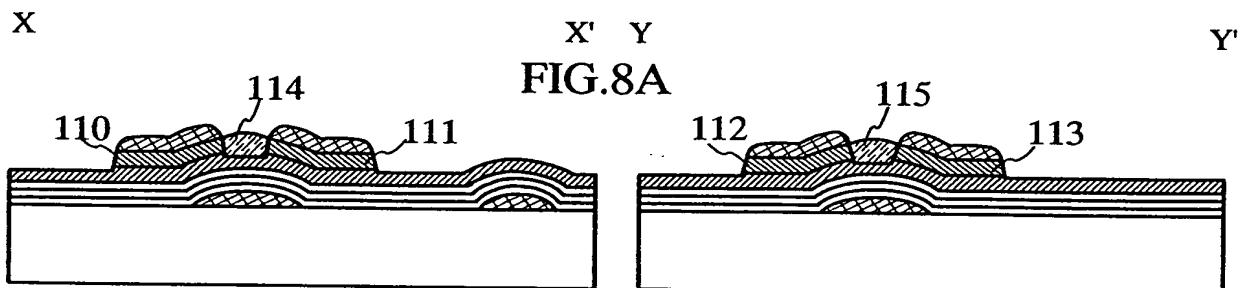
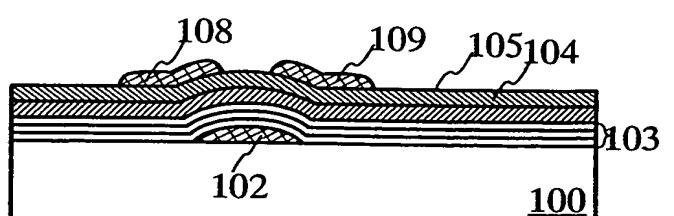
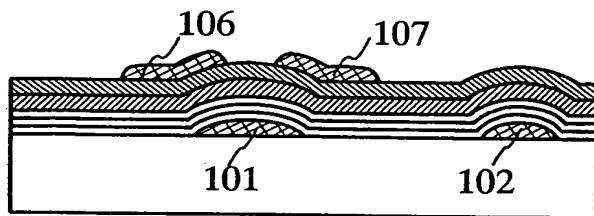


FIG.8C

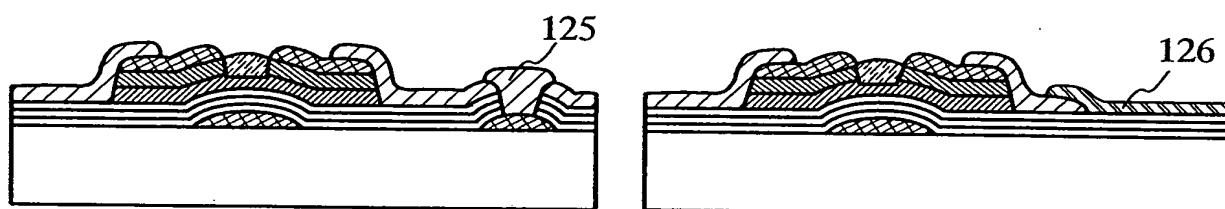


FIG.8D

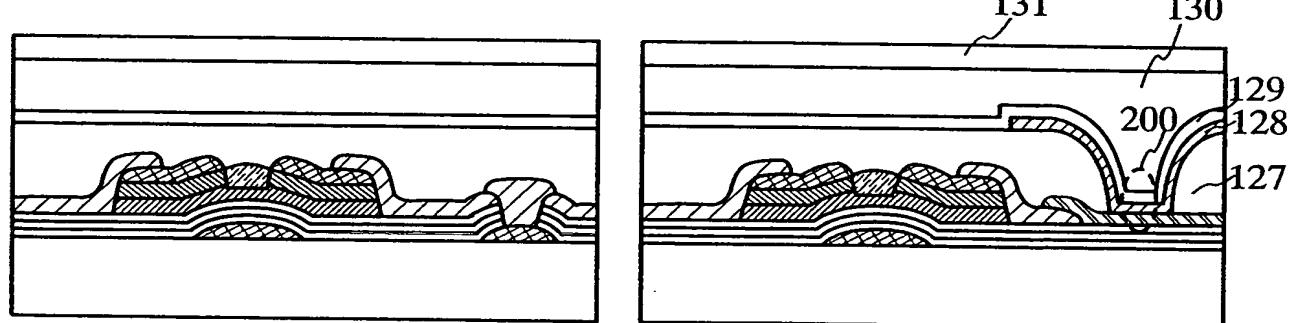


FIG.8E

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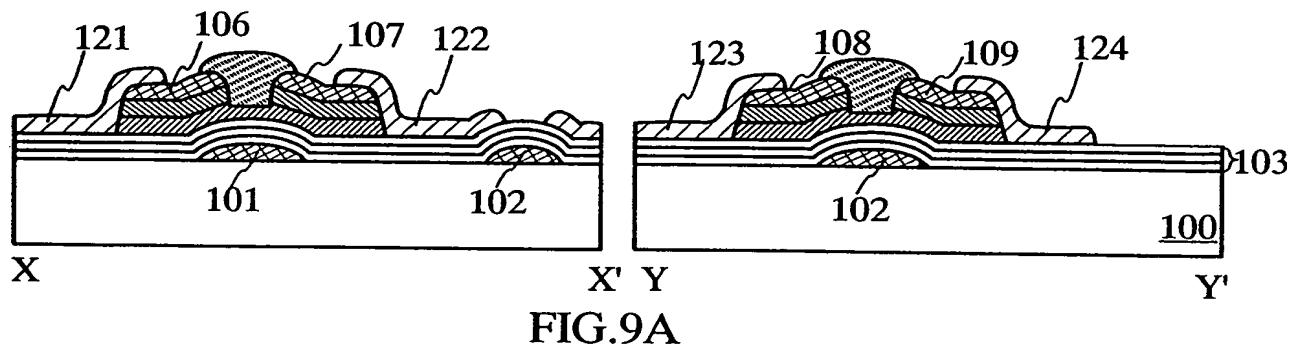


FIG.9A

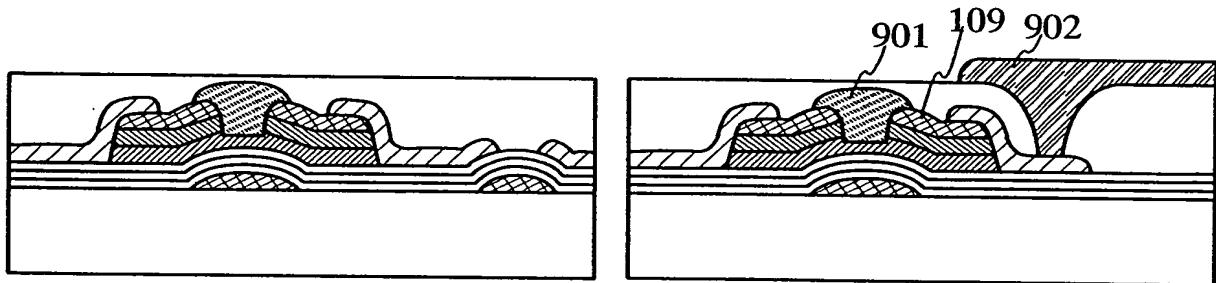


FIG.9B

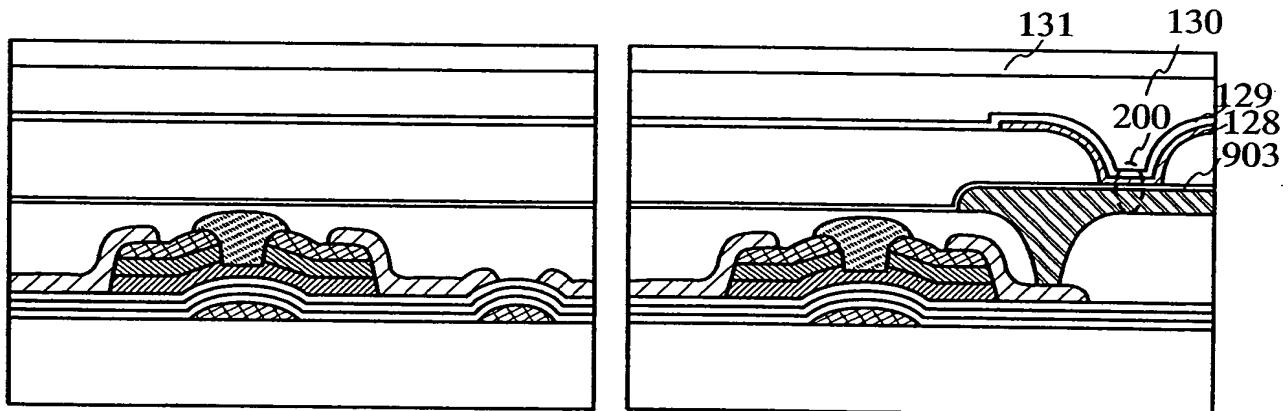


FIG.9C

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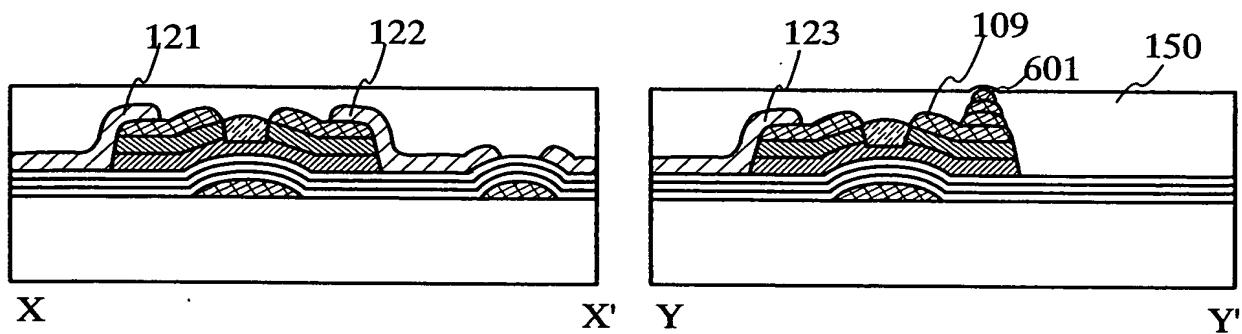


FIG.10A

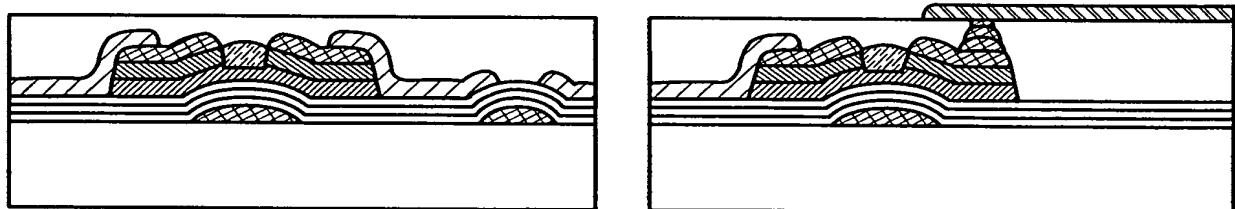


FIG.10B

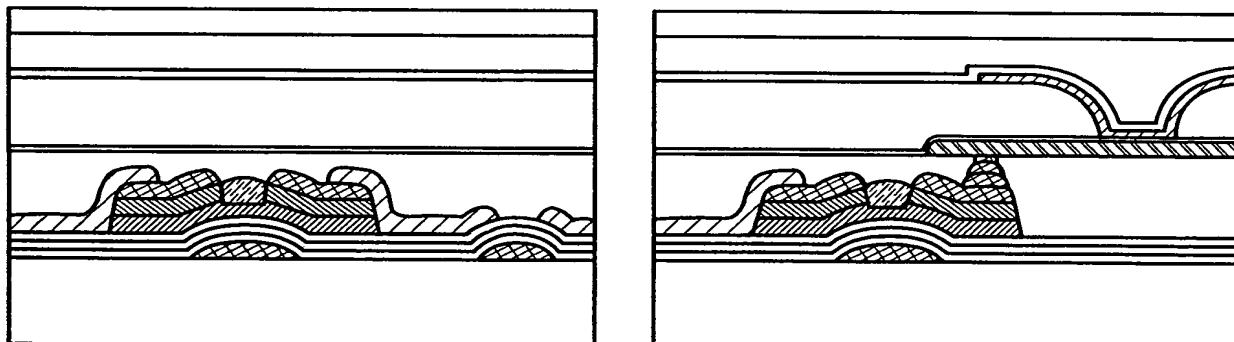
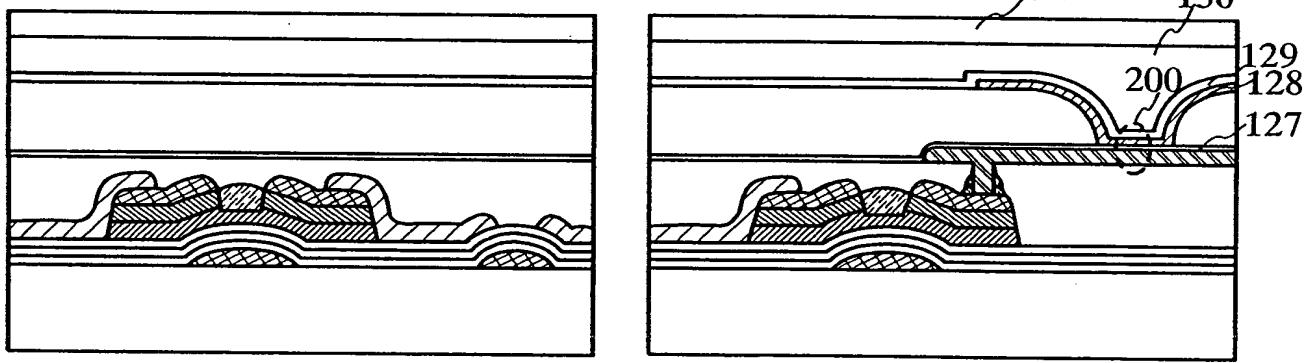
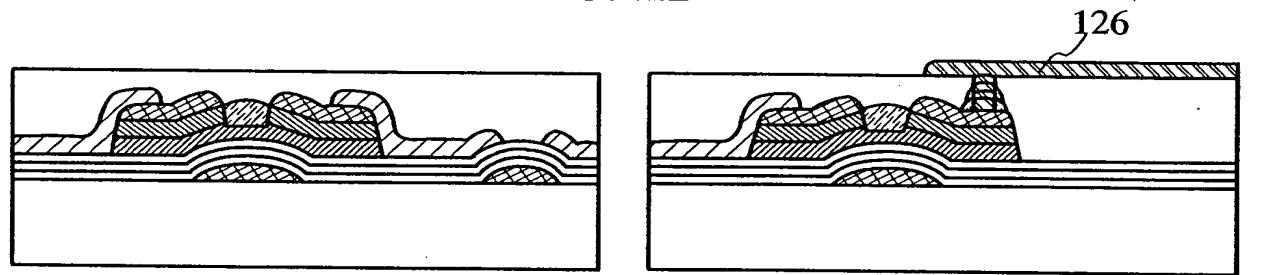
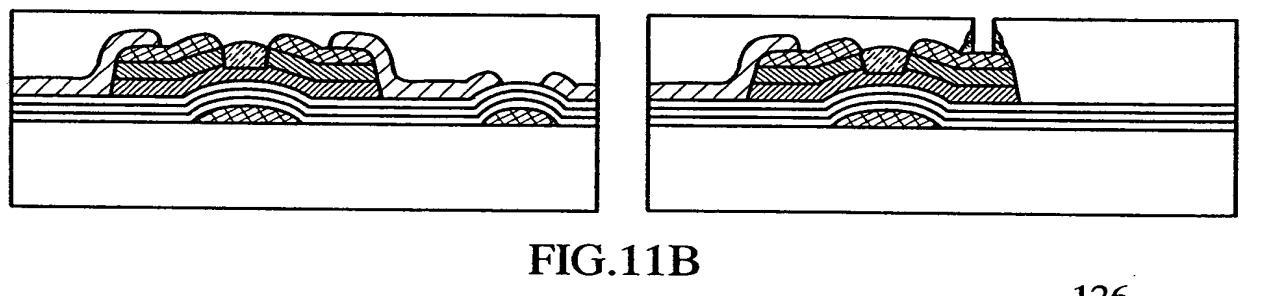
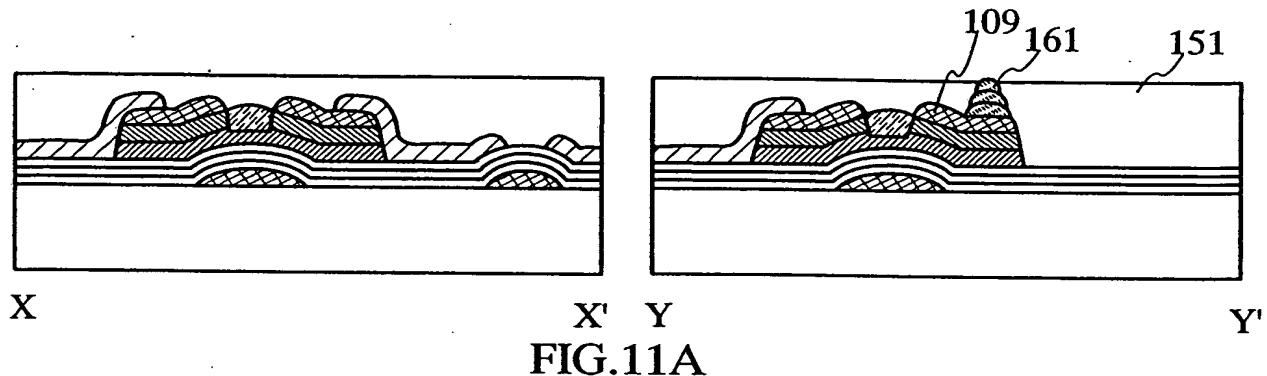


FIG.10C

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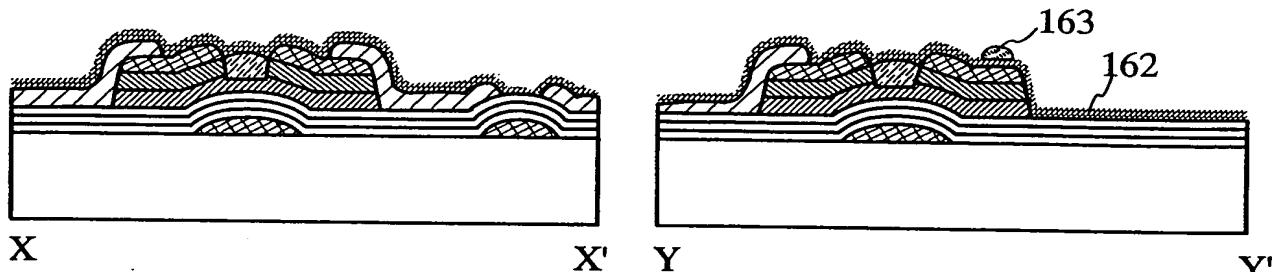


FIG.12A

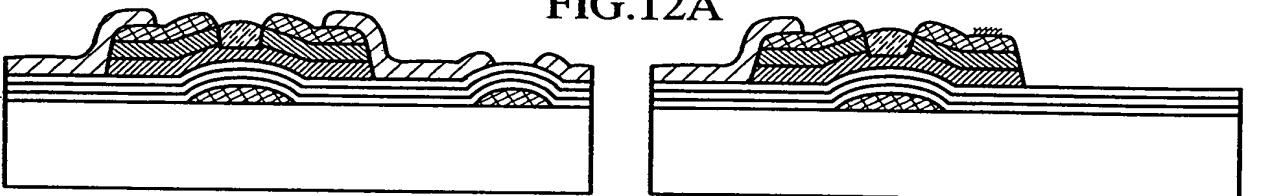


FIG.12B

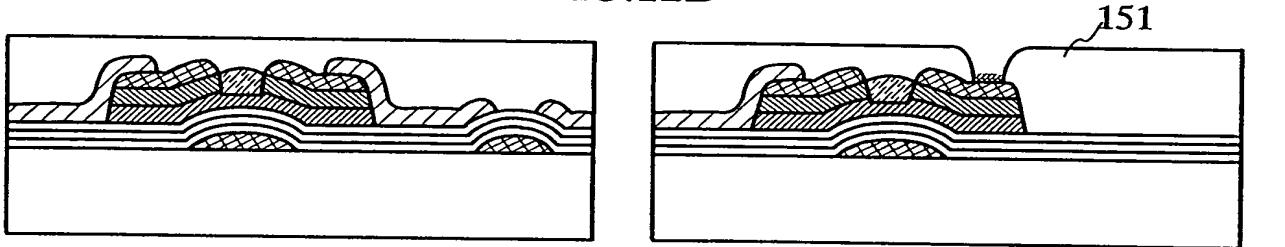


FIG.12C

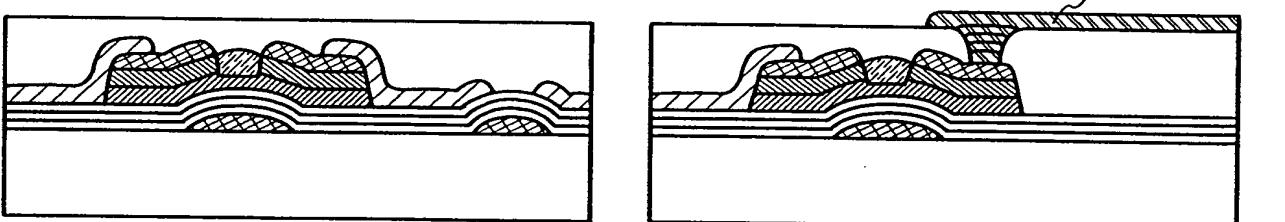


FIG.12D

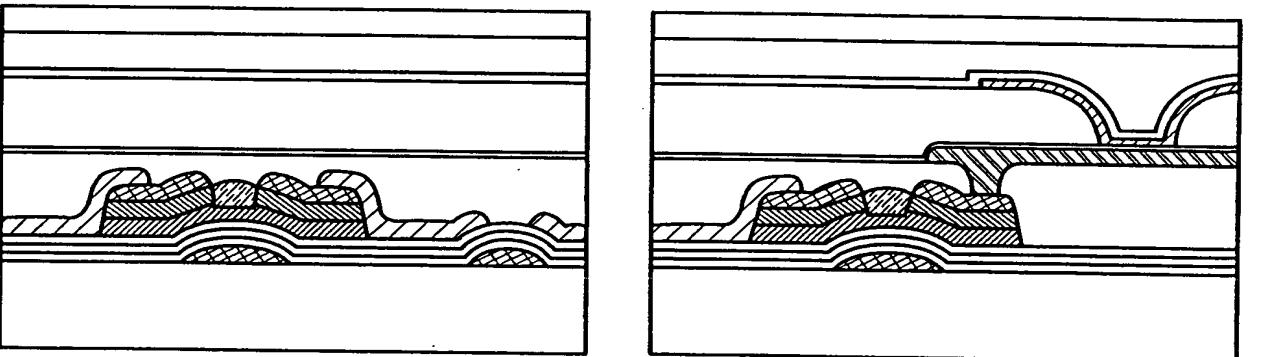


FIG.12E

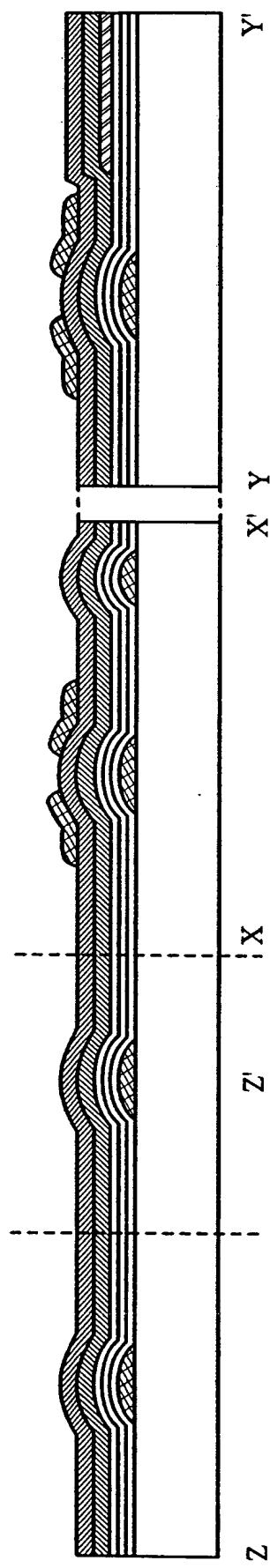


FIG.13A

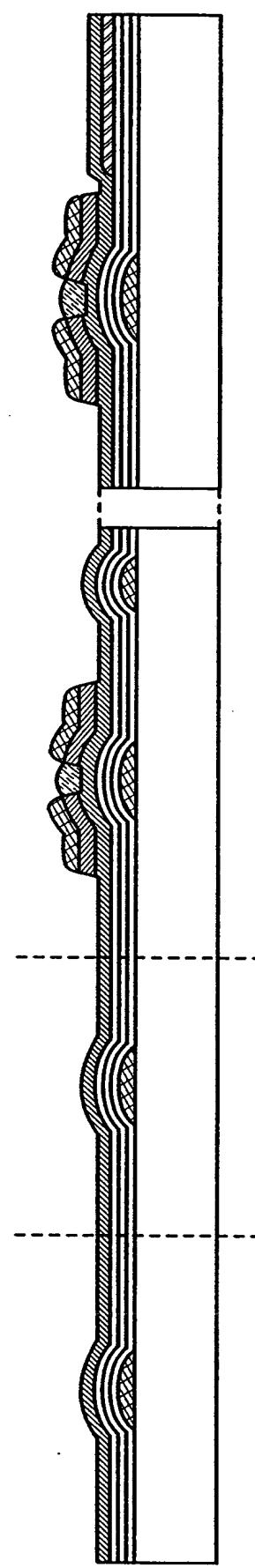


FIG.13B

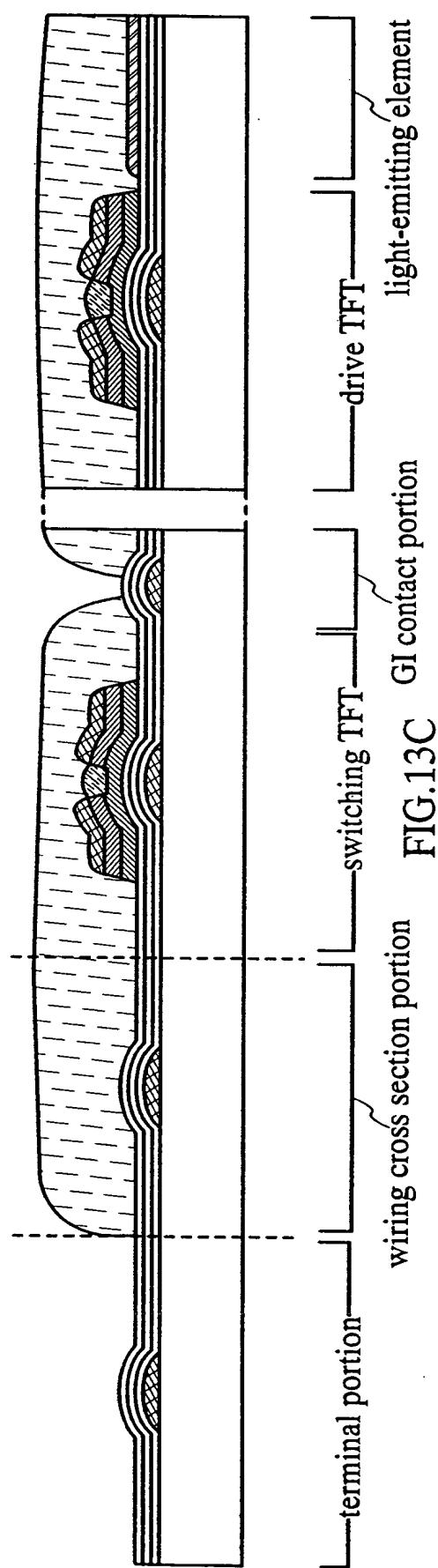


FIG.13C

terminal portion
switching TFT
drive TFT
GI contact portion
light-emitting element
wiring cross section portion

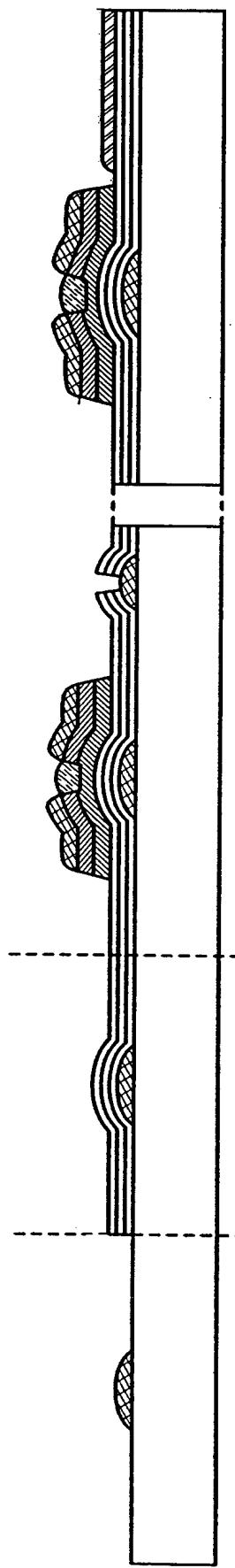


FIG.14A

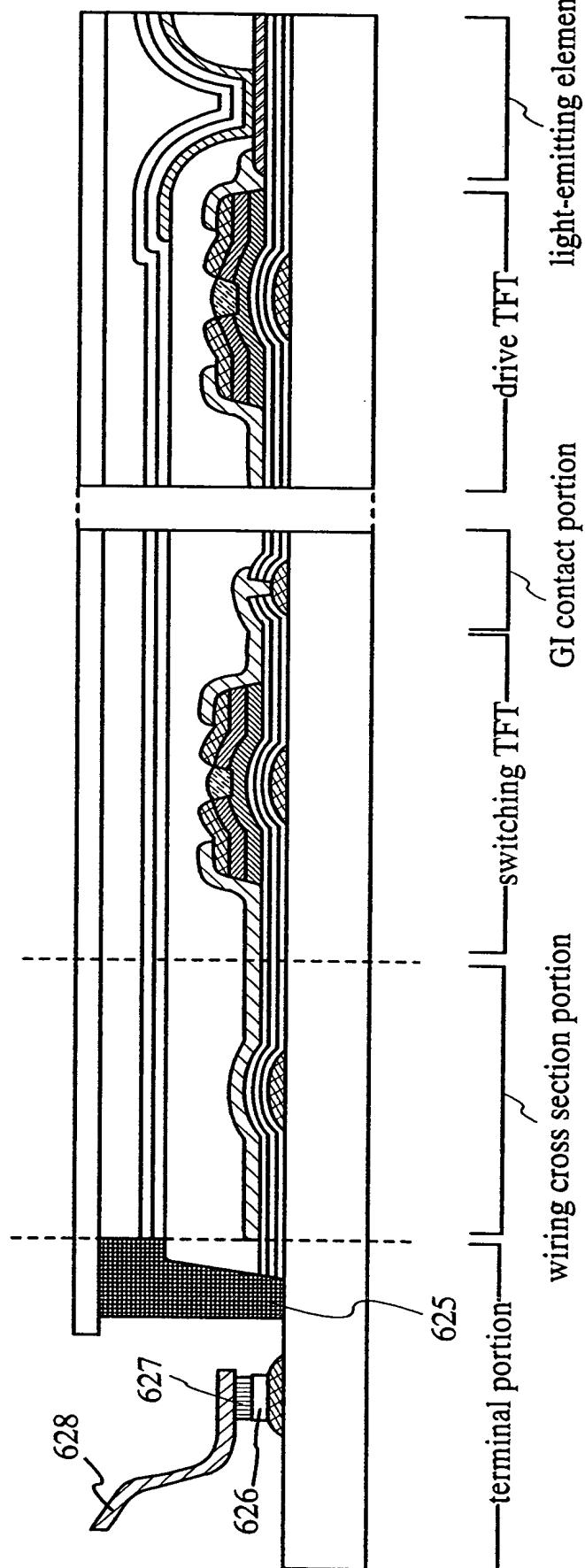


FIG.14B

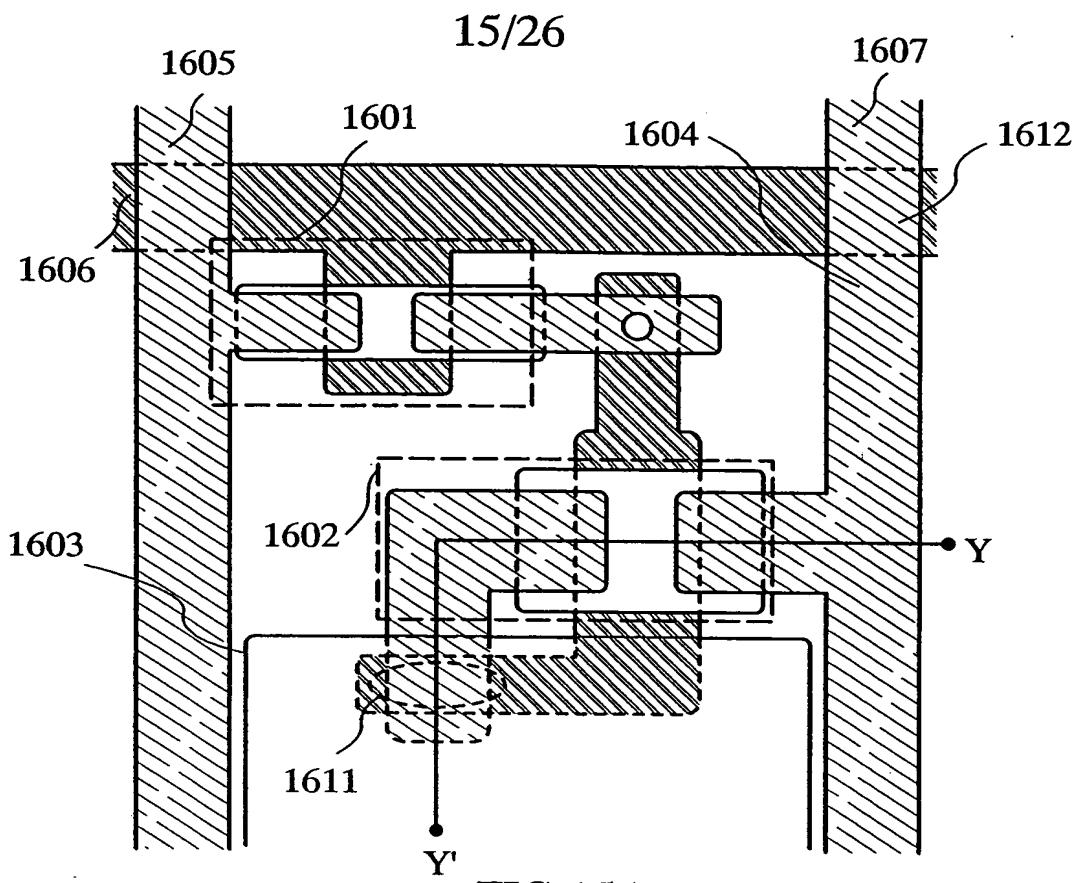


FIG.15A

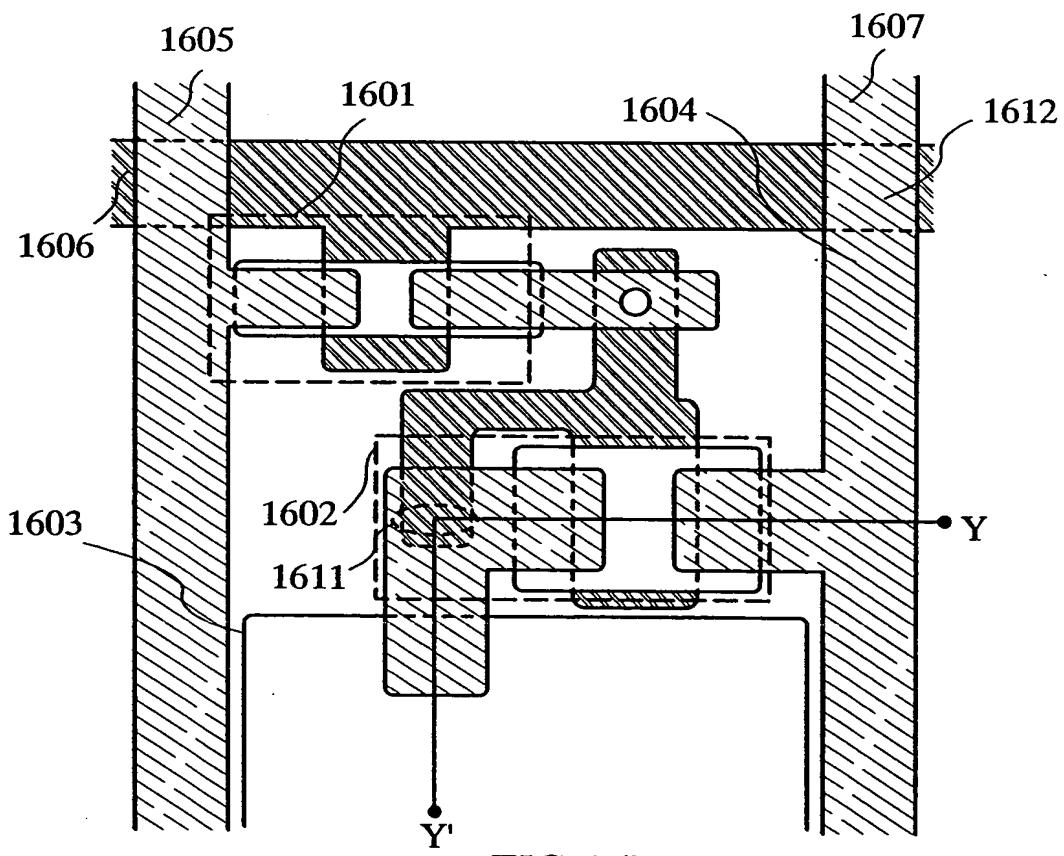


FIG.15B

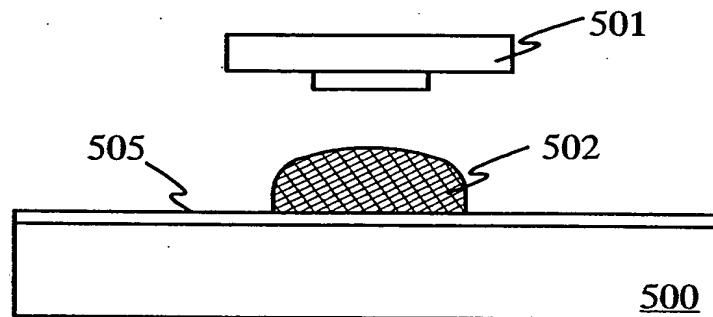


FIG.16A

drying and baking

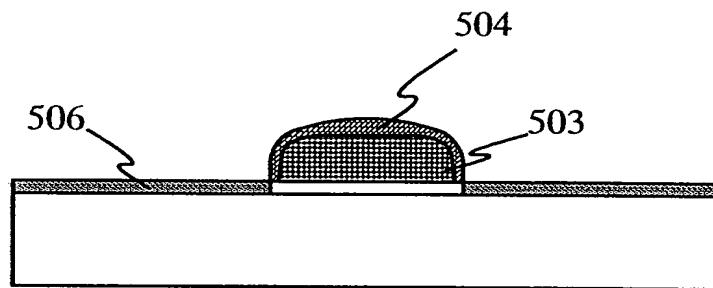


FIG.16B

baking in the atmosphere containing oxygen or oxygen plasma treatment

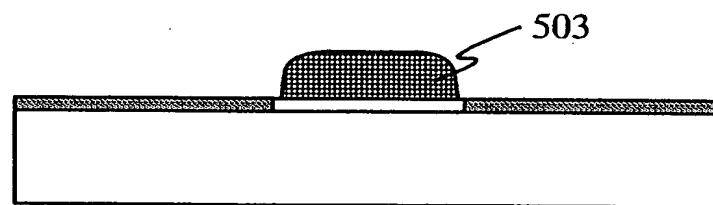


FIG.16C

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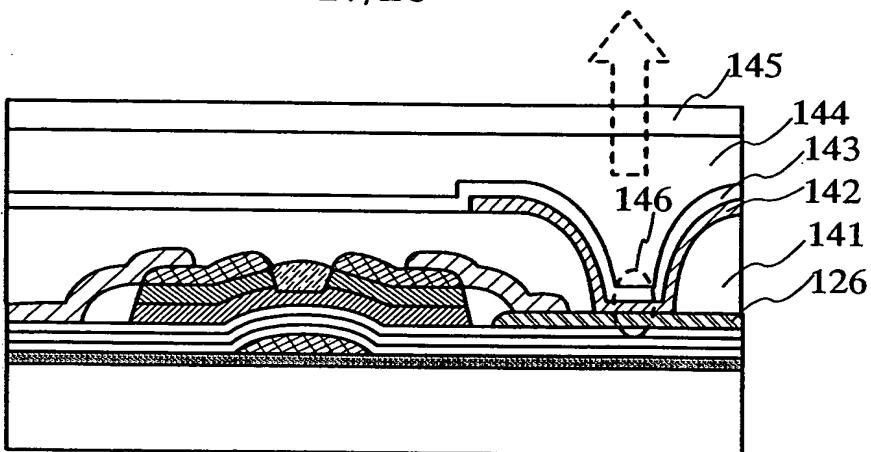


FIG.17A

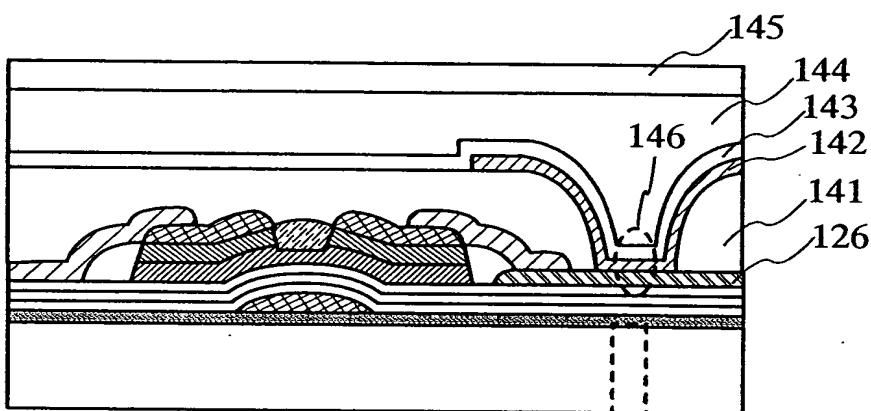


FIG.17B

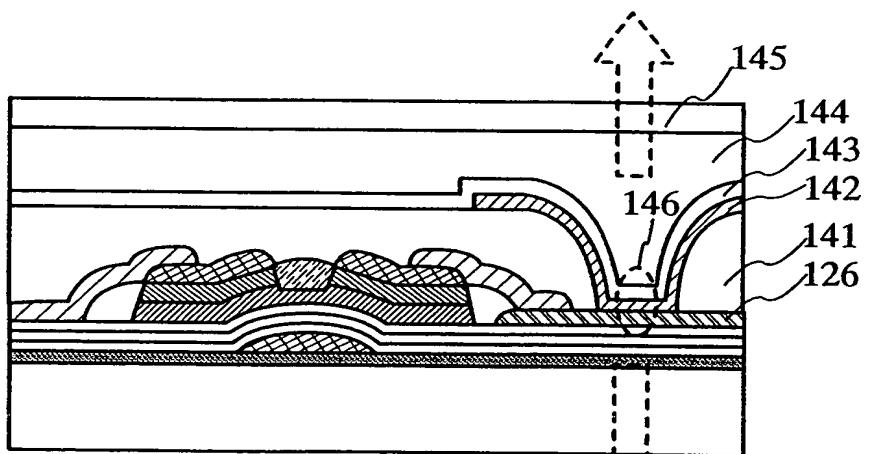


FIG.17C

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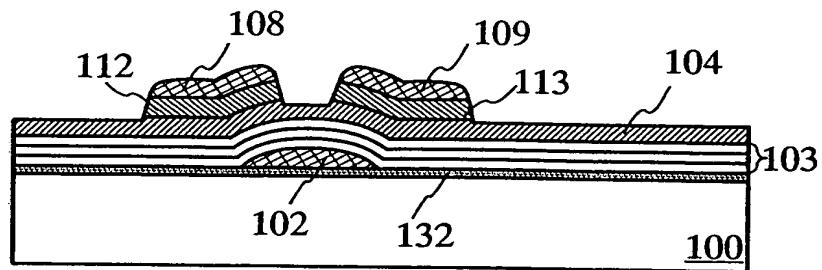


FIG.18A

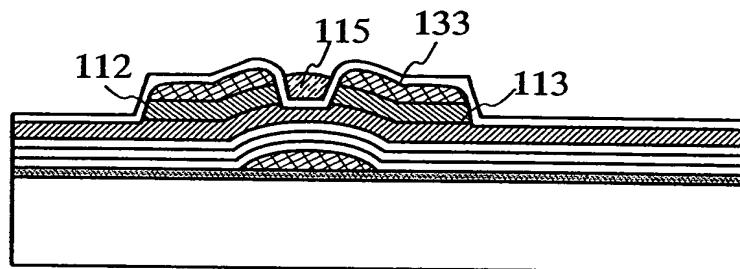


FIG.18B

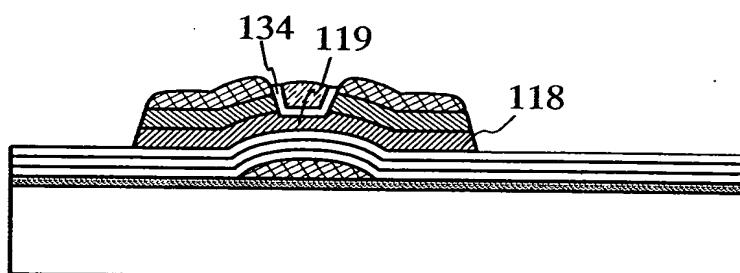


FIG.18C

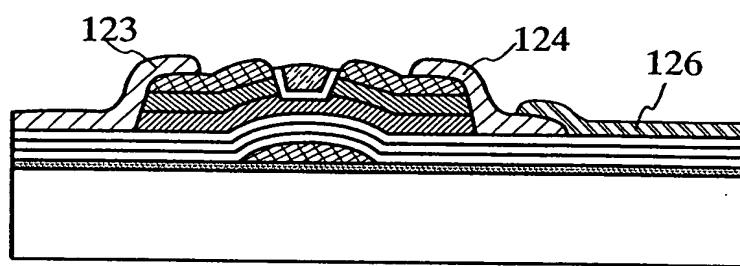


FIG.18D

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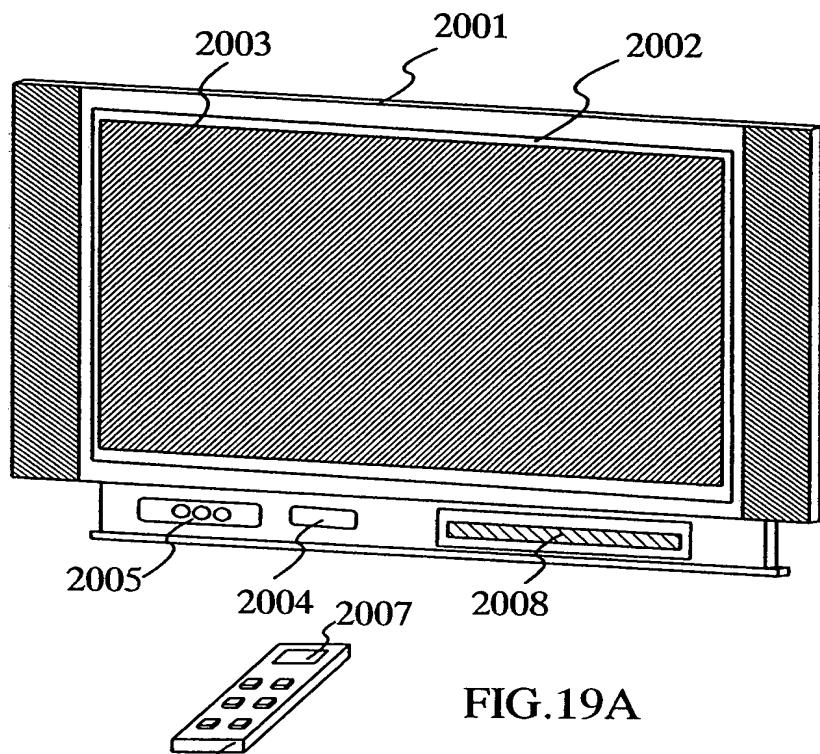


FIG.19A

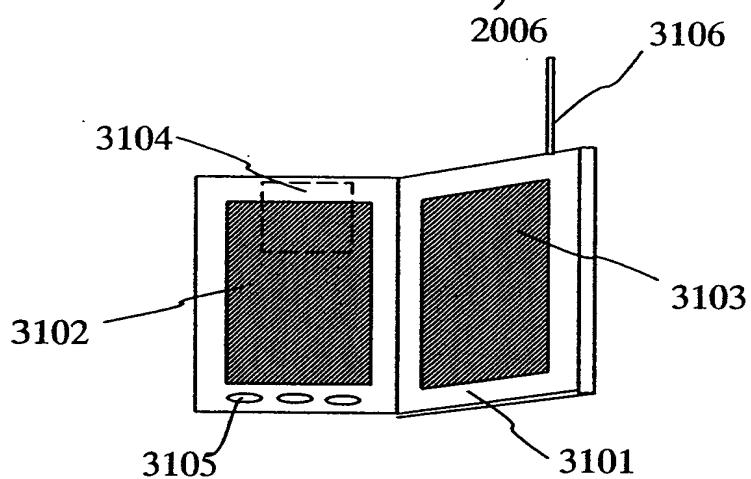


FIG.19B

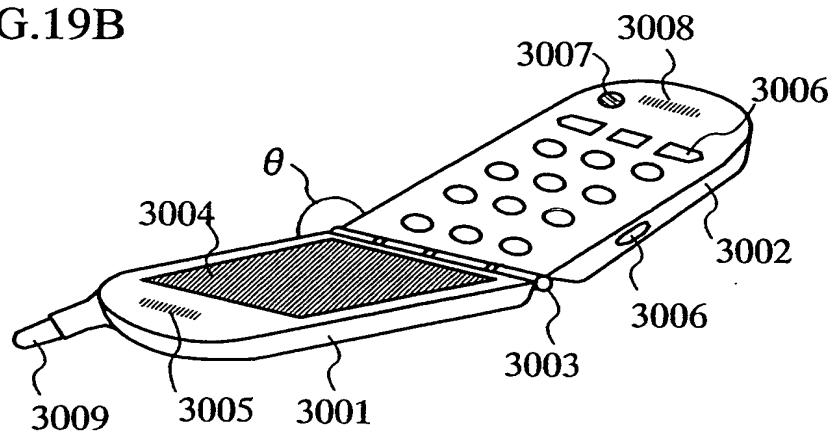


FIG.19C

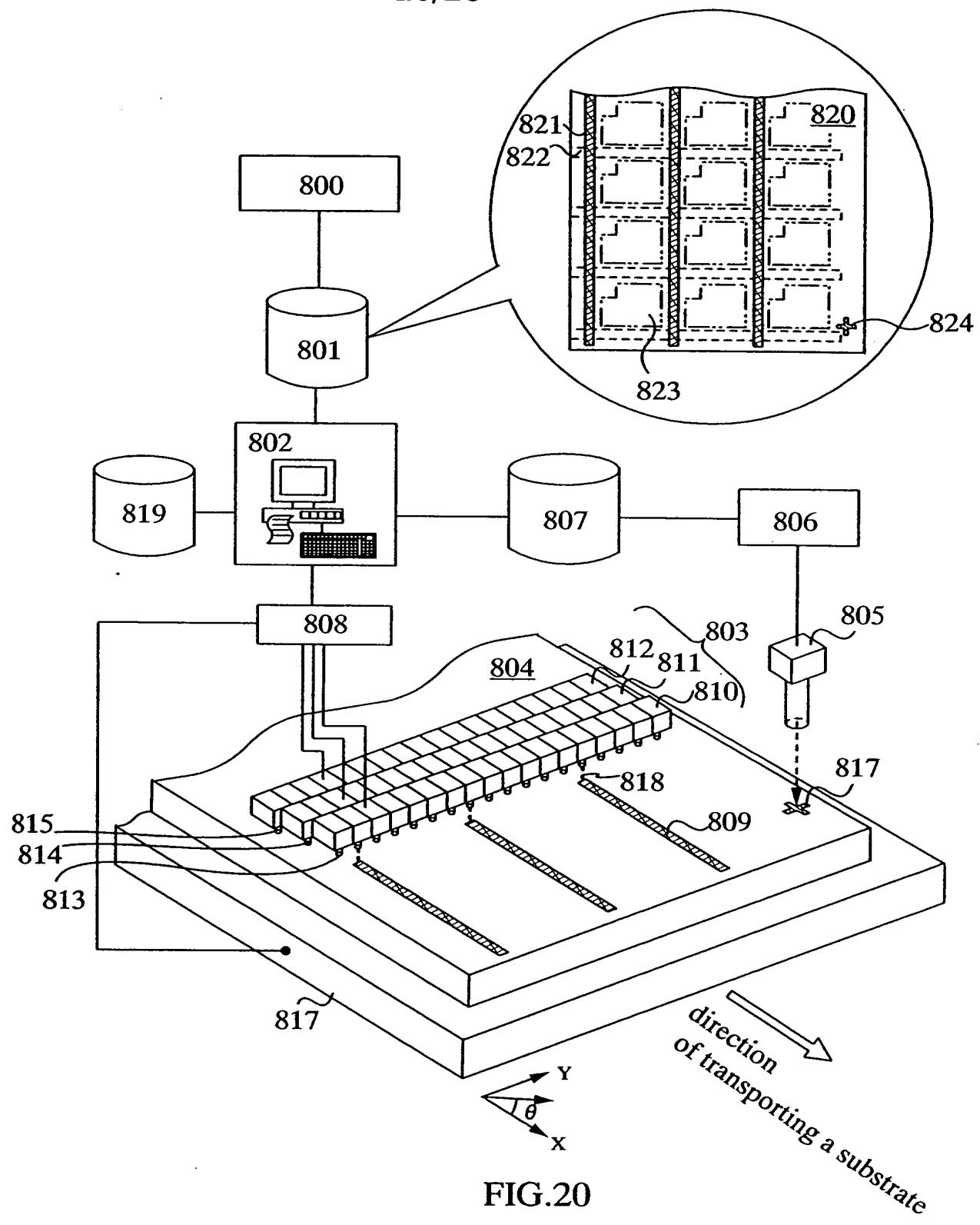


FIG.20

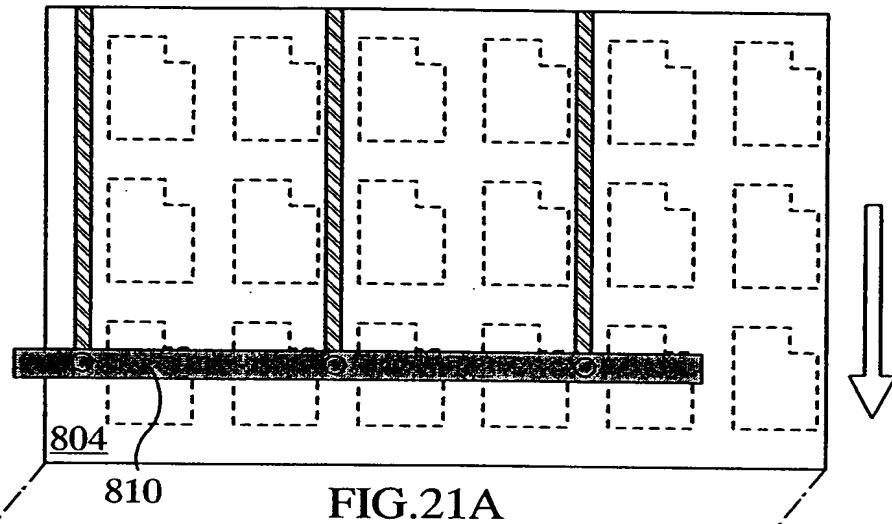


FIG.21A

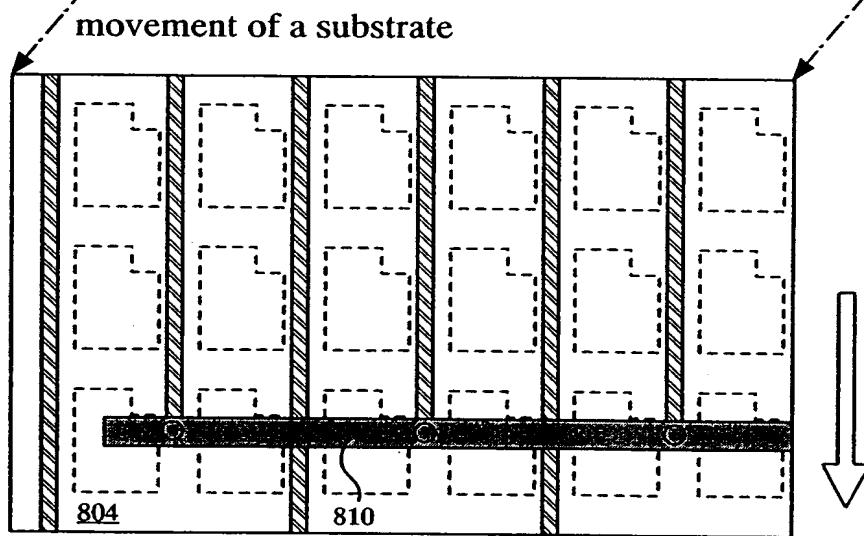


FIG.21B

movement of a substrate

direction of transporting a substrate

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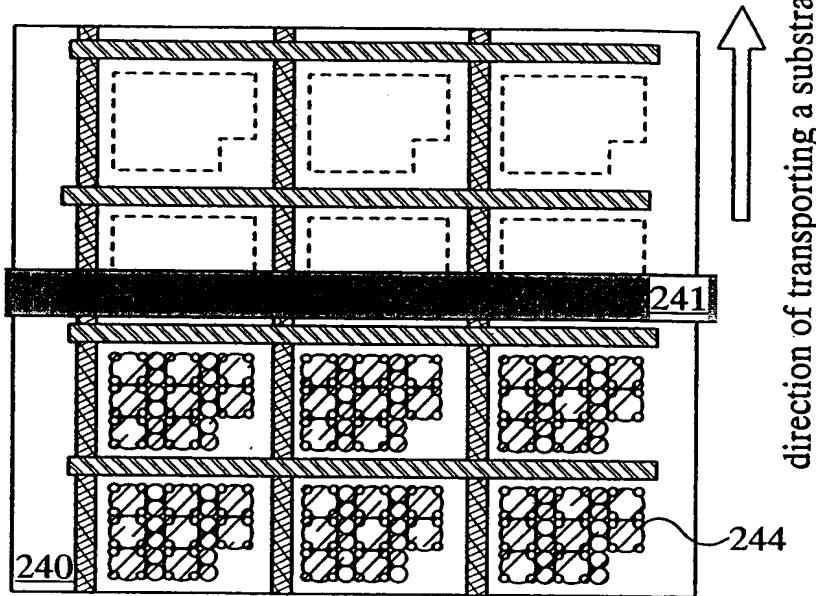


FIG.22A

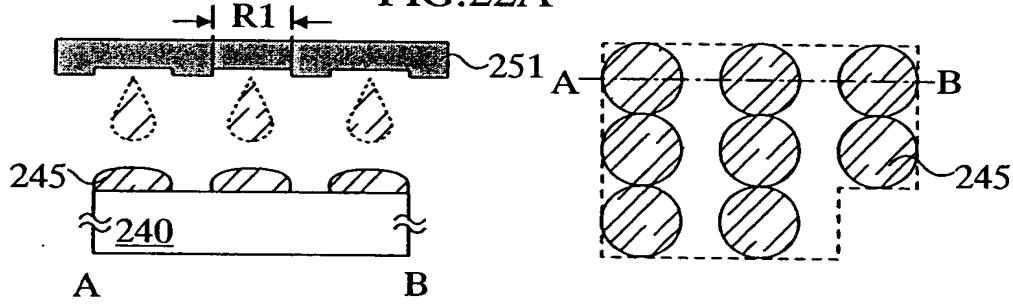


FIG.22B

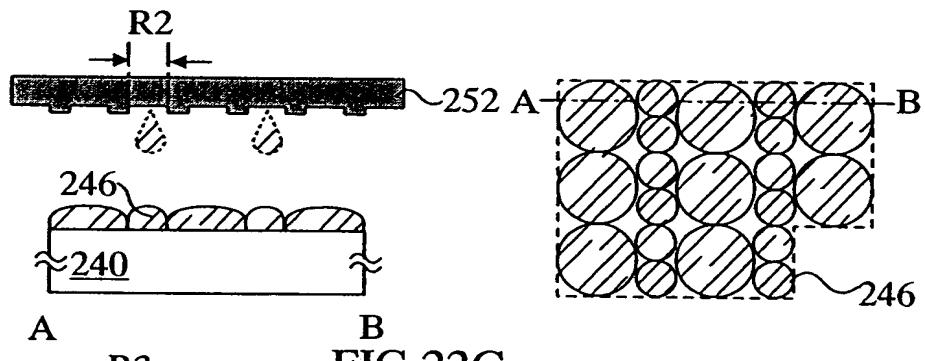


FIG.22C

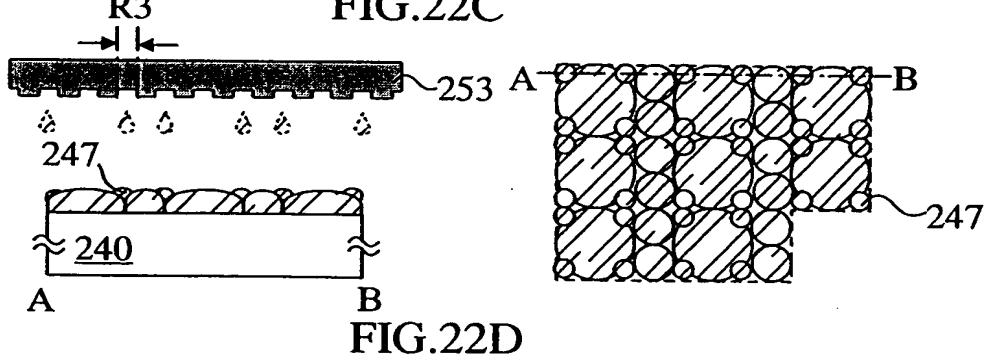


FIG.22D

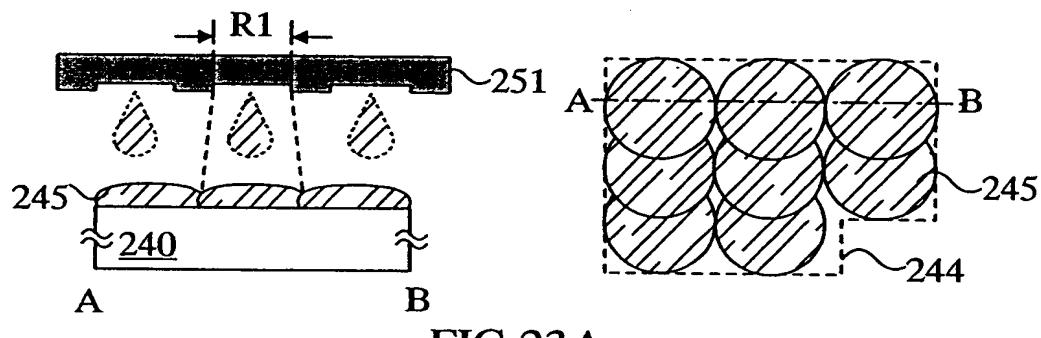


FIG. 23A

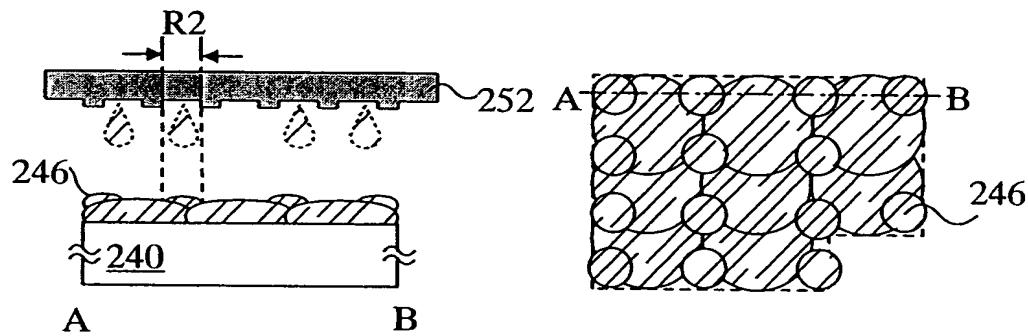


FIG. 23B

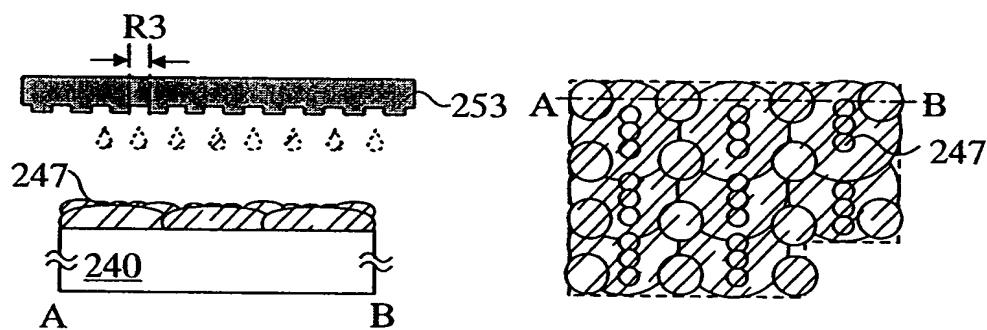


FIG. 23C

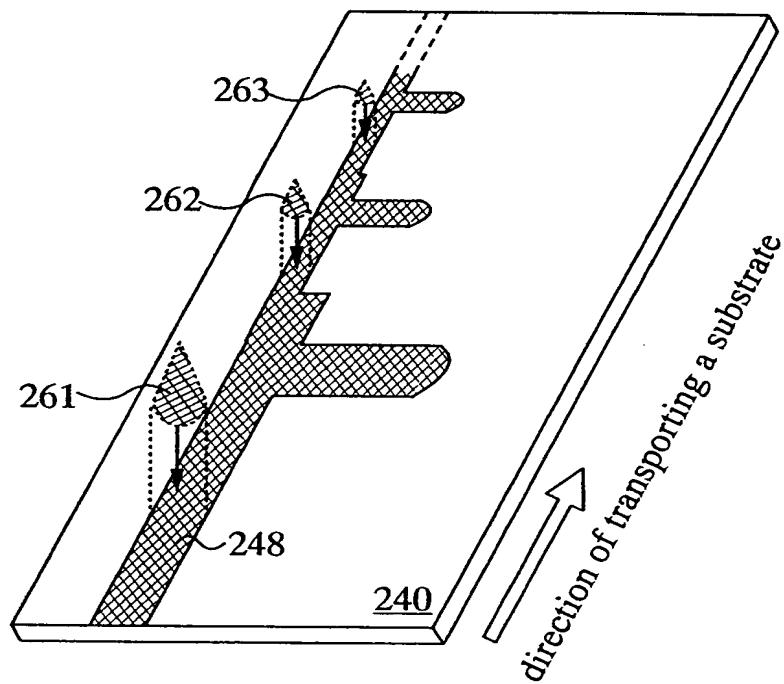
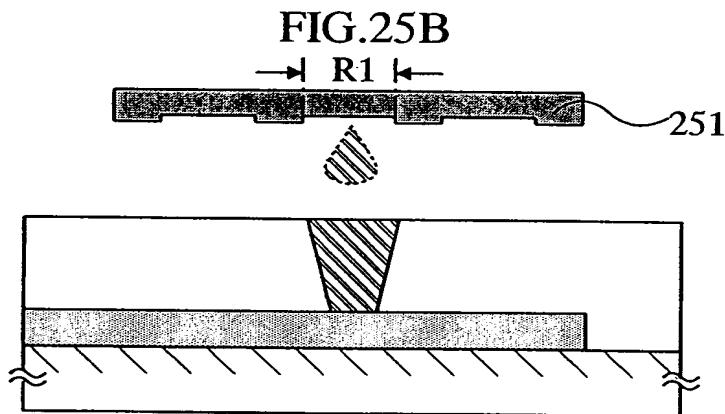
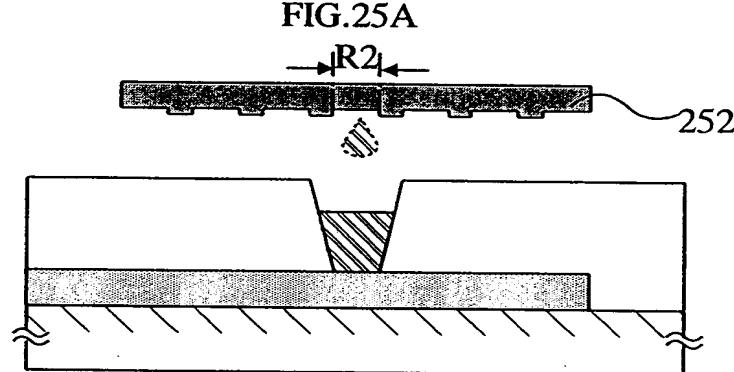
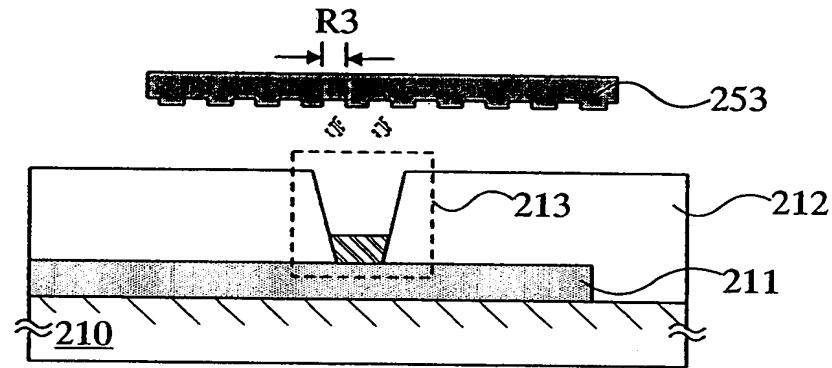


FIG.24



DESCRIPTION OF NUMERALS

100:Substrate, 101-102:Gate electrode layer, 103:Gate insulating film,
104:Semiconductor film, 105:N-type semiconductor film, 106-109:Source or drain
electrode, 110-113:Source or drain region, 114-115:Insulating film, 116:Island-like
semiconductor film, 117:Channel region, 118:Island-like semiconductor film,
119:Channel region, 120:Wiring, 121-124:Source or drain wiring, 125:Conductor,
126:Pixel electrode, 127:Partition wall, 128:Organic compound layer, 129:Electron
injecting electrode, 130:Passivation film, 131:Opposing substrate, 132:Titanium oxide
film, 133:Silicon nitride film, 134:Insulating film, 141:Partition wall, 142:Organic
compound layer, 143:Electron injecting electrode, 144:Passivation film, 145:Opposing
substrate, 146:Light-emitting element, 150:Planarized film, 151:Planarized film,
152:Source or drain wiring, 161:Pillar insulator, 162:Liquid-shedding material,
163:Mask, 200:Light-emitting element, 210:Substrate, 211:Semiconductor or Conductor,
212:Insulator, 500:Glass substrate, 501:Nozzle, 502:Nano paste, 503:Conductor
containing metal chains, 504:Film formed by organic ingredients, 626:Terminal
electrode, 627:Anisotropic conductive film, 628:FPC, 652:Terminal portion, 654:Pixel
TFT, 800:Circuit design tool, 801:Data of thin film pattern, 802:Computer, 805:Imaging
means, 806:Image processing device, 807:Position information of alignment marker,
808:Controller, 816:XYθ stage, 817:Alignment marker, 819:Database, 2001:Housing,
2002:Display module, 2003:Main-screen, 2004:Modem, 2005:Receiver, 2006:Wireless
remote control, 2007:Display portion, 2008:Sub-screen, 3001:Display panel,
3002:Operation panel, 3003:Connecting portion, 3004:Display portion, 3005:Voice
output portion, 3006:Operation key, 3007:Power source switch, 3008:Voice input
portion, 3009:Antenna, 3101:Main body, 3102:Display portion, 3103:Display portion,
3104:Memory medium, 3105:Operation switch, 3106:Antenna